



# iPhone 11 Pro Motherboard Separating & Recombining

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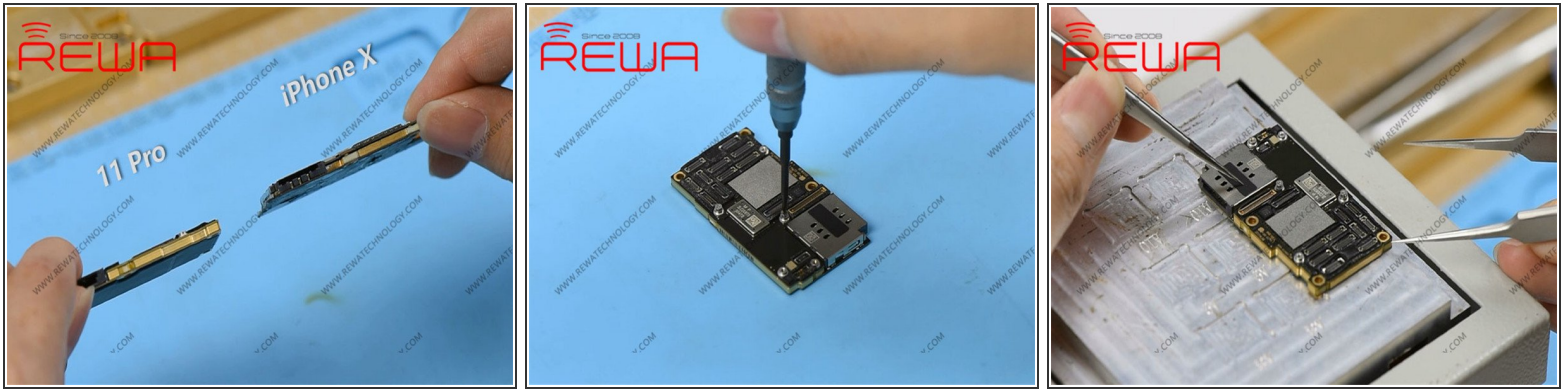
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## INTRODUCTION

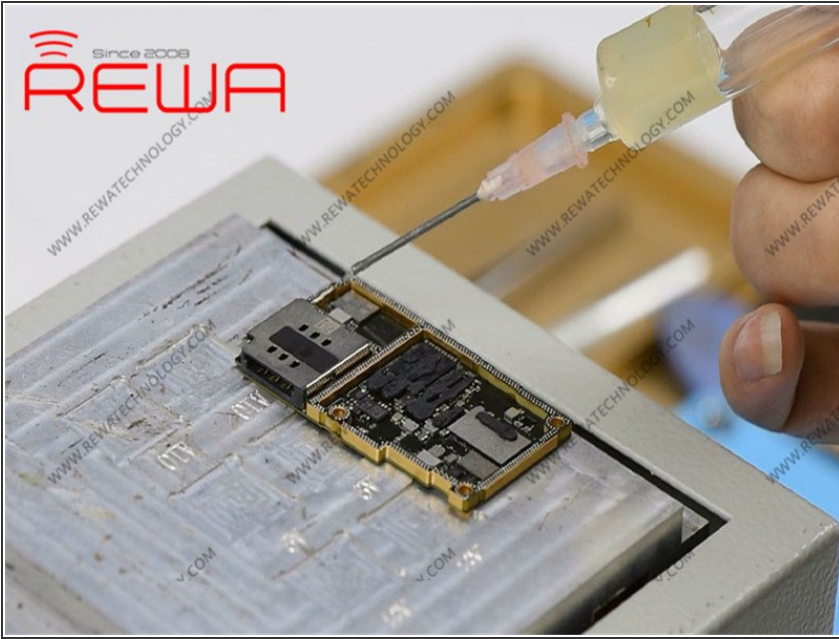
As we all know, iPhone new series have undergone considerable changes on both inside and outside. Especially on the motherboard. How will these changes affect the repair industry? Will it make third-party repair harder or easier? Find the answer by yourself now.

## Step 1 — iPhone 11 Pro Motherboard Separation



- Compared with iPhone X series, iPhone 11 Pro's motherboard is smaller with a much denser component array. It is also thicker.
- Remove the graphite thermal transfer material with tweezers first.
- ⚠ Fit two screws into the screw holes reserved on the motherboard.
- Place the motherboard on the heating platform to heat for 3 minutes.
- Clamp the screws fitted into the screw holes with tweezers and pick up the upper layer with tweezers vertically.
- Continue to pick up the lower layer.

## Step 2 — iPhone 11 Pro Motherboard Recombination Without Reballing



- Place the lower layer on the heating platform to heat for 10 seconds. Apply some Paste Flux to the third space PCB evenly. Get the upper layer in position and heat for about 5 minutes.
- Then, press the SIM card reader with the tweezers and push the upper layer with another tweezers slightly. If the upper layer returns to the previous position automatically, then the soldering process is completed.

## Step 3



- Follow the video guide and learn how to separate and recombine the motherboard step by step. You can check out the video [here](#).
- Credit: [REWA Technology](#)